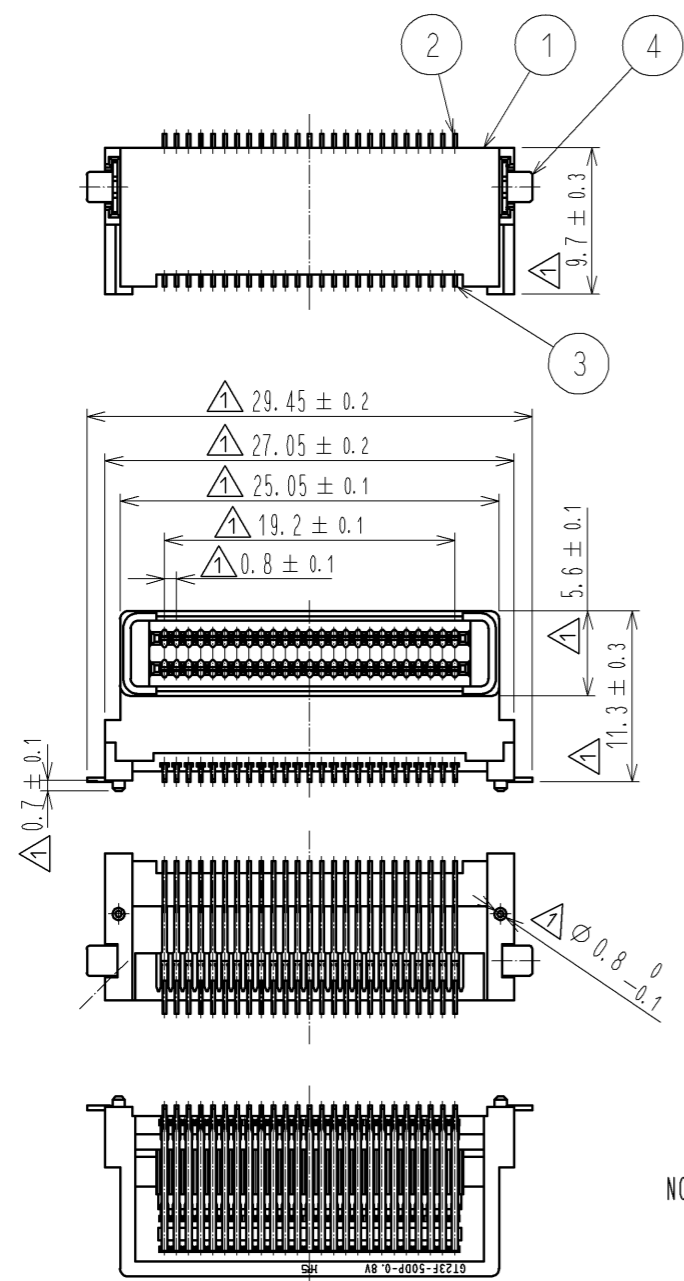
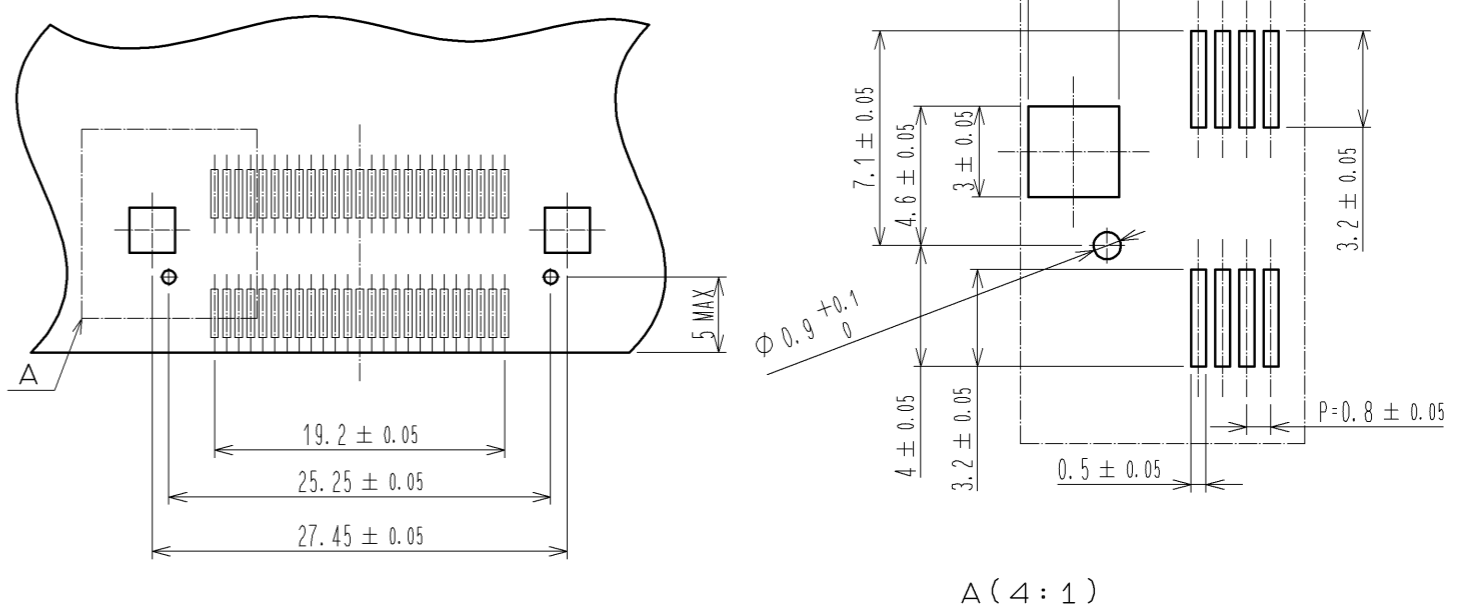


ELV, RoHS COMPLIANT



Recommended PCB layout



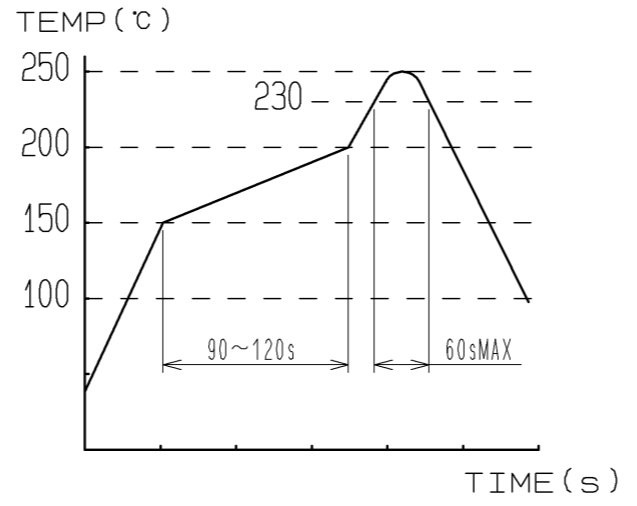
HRS DRAWING FOR REFERENCE

NOTE 1. CO-PLANARITY SHALL BE 0.1 MAX.
2. RECOMMENDED SOLDER THICKNESS=0.15

RECOMMENDED TEMPERATURE PROFILE FOR REFLOW

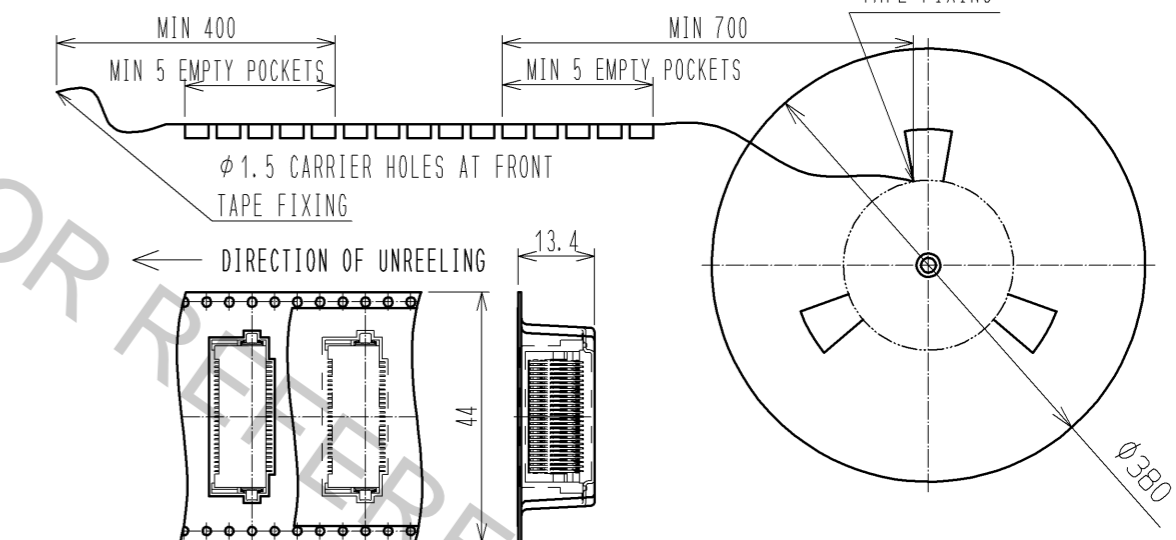
- 1. PEAK : 250°C
- 2. OVER230°C : 60sec MAX
- 3. PREHEAT : 150~200°C, 90~120sec
- 4. NO. OF CYCLES : 2 TIMES MAX

*This temperature profile is the recommended value. The temperature profile may differ depending on the cream solder, the manufacturer, the PC Board size, and other mounting materials, etc. Please confirm the mounting condition before applying the recommended temperature profile.

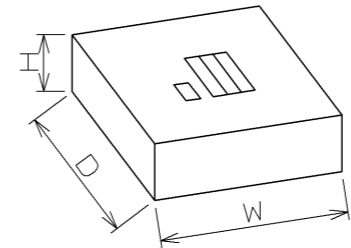


PACKING STYLE

1. Place connectors into an embossed carrier tape.



2. Put a reel into a cardboard.



W=(405) (mm)
D=(405) (mm)
H=(49) (mm)

2	BRASS	Contact:GOLD PLATING. Mounting:TIN PLATING	4	BRASS	TIN PLATING
1	PA	BLACK	3	BRASS	Contact:GOLD PLATING. Mounting:TIN PLATING
NO.	MATERIAL	FINISH, REMARKS	NO.	MATERIAL	FINISH, REMARKS
UNITS	mm	SCALE	2:1	COUNT	11
		DESCRIPTION OF REVISIONS	DESIGNED	CHECKED	DATE
		DIS-T-001896	HH. TSUKUMO	TY. TAKAHASHI	10.09.30
APPROVED: AR. SHIRAI		10.03.29	DRAWING NO. EDC3-167667-00		
CHECKED: TY. TAKAHASHI		10.03.29	PART NO. GT23F-50DP-0.8H		
DESIGNED: TY. SAKASHITA		10.03.29	CODE NO. CL773-0008-0-00		
DRAWN: KT. MATSUDA		10.03.26			